

General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
60 V	30 mΩ	5.9 A
-60 V	48 mΩ	-4.7 A

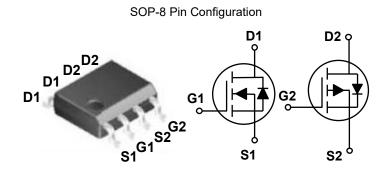
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Features

Fast switching

Green Device Available

Suit for 4.5V Gate Drive Applications



Applications

• DC Fan

Motor Drive Applications

- Networking
- Half / Full Bridge Topology

Symbol	Parameter	Ra	Rating		
V _{DS}	Drain-Source Voltage	60	-60	V	
V _{GS}	Gate-Source Voltage	±20	±20	V	
I _D	Drain Current - Continuous (T _A =25°C)	5.9	-4.7	A	
D	Drain Current - Continuous (T _A =70°C)	4.7	-3.8	Α	
I _{DM}	Drain Current - Pulsed (NOTE 1)	23.6	-18.8	Α	
EAS	Single Pulse Avalanche Energy (NOTE 2)	26.4	54.4	mJ	
IAS	Single Pulse Avalanche Current (NOTE 2)	23	33	Α	
P _D	Power Dissipation (T _A =25°C)	2.	.01	W	
I D	Power Dissipation - Derate above 25°C	0.	0.02		
TJ	Operating Junction Temperature Range	-55 te	-55 to 150		
T _{STG}	Storage Temperature Range	-55 te	-55 to 150		
/larking Code		BG030 , DS6701			

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{ etaJA}$	Thermal Resistance Junction to Ambient		62	°C/W
$R_{ extsf{ heta}JC}$	Thermal Resistance Junction to Case		38	°C/W





N Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

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Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit		
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V		
lana	Drain-Source Leakage Current	V_{DS} =60V , V_{GS} =0V , T_{J} =25°C			1	uA		
IDSS		V_{DS} =48V , V_{GS} =0V , T_{J} =125°C			10	uA		
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA		

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =5A		25	30	mΩ
		V _{GS} =4.5V , I _D =3A		28	36	11152
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.6	2.5	V
gfs	Forward Transconductance	V _{DS} =10V , I _D =3A		10		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			16.6	24	
Q_gs	Gate-Source Charge	V _{DS} =30V , V _{GS} =10V , I _D =5A (NOTE 3 ∖ 4)		2.2	4.4	nC
Q_{gd}	Gate-Drain Charge			3.9	8	
T _{d(on)}	Turn-On Delay Time	V _{DD} =30V , V _{GS} =10V , R _G =6Ω ,		4.6	9	
Tr	Rise Time			14.8	28	nS
T _{d(off)}	Turn-Off Delay Time	I _D =1A(NOTE 3 ∖ 4)		27.2	52	115
T _f	Fall Time			7.8	15	
C _{iss}	Input Capacitance			1180	1720	
C _{oss}	Output Capacitance	V _{DS} =30V , V _{GS} =0V , F=1MHz		68	100	pF
C _{rss}	Reverse Transfer Capacitance			45	70	
Rg	Gate resistance	V_{GS} =0V , V_{DS} =0V , F=1MHz		2.1	4.2	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	$V_{G}=V_{D}=0V$, Force Current			5.9	А
I _{SM}	Pulsed Source Current				11.8	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A , T _J =25°C			1	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

2. V_{DD} =25V, V_{GS} =10V, L=0.1mH, N-CH I_{AS}=23A, P-CH I_{AS}=33A, R_G=25, Starting T_J=25°C.

- 3. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.



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Characteristics Curves

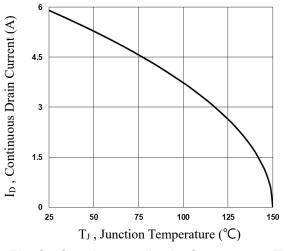
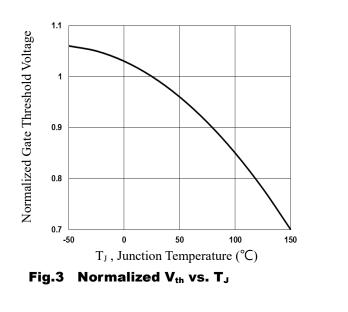
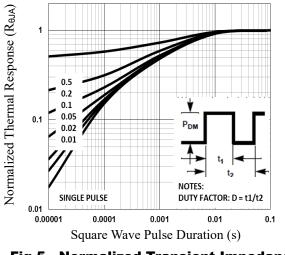


Fig.1 Continuous Drain Current vs. Tc







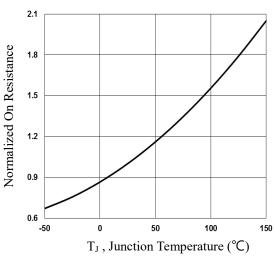
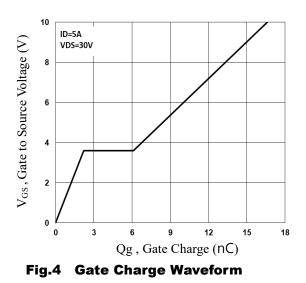


Fig.2 Normalized RDSON vs. T.



I_D, Continuous Drain Current (A) 10 10us 1 100us 1ms 0.1 10ms 100ms DC TA=25°C 0.01 0.1 10 100 1 V_{DS}, Drain to Source Voltage (V) Fig.6 Maximum Safe Operation Area





P Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

••								
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit		
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V , I _D = -250uA	-60			V		
lana	Drain-Source Leakade Current	V_{DS} = -60V , V_{GS} = 0V , T_{J} =25°C			-1	uA		
IDSS		V_{DS} = -48V , V_{GS} = 0V , T_J =125°C			-10			
I _{GSS}	Gate-Source Leakage Current	V_{GS} = ±20V , V_{DS} = 0V			±100	nA		

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = -10V , I _D = -4A		40	48	mΩ
		V _{GS} = -4.5V , I _D = -3A		53	68	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D = -250uA	-1.2	-1.6	-2.5	V
gfs	Forward Transconductance	V _{DS} = -10V , I _D = -3A		10		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} = -30V , V _{GS} = -10V ,		22.4	31	
Q_gs	Gate-Source Charge	v _{DS} 30v , v _{GS} 10v , I _D = -4A (NOTE 2 ∖ 3)		4.1	6	nC
Q_gd	Gate-Drain Charge			5.2	7	
T _{d(on)}	Turn-On Delay Time			13	25	
Tr	Rise Time	V _{DD} = -30V , V _{GS} = -10V ,		42.4	81	nS
T _{d(off)}	Turn-Off Delay Time	$R_G = 6\Omega$, $I_D = -1A$ (NOTE 2 \cdot 3)		64.6	123	115
T _f	Fall Time			16.4	31	
C _{iss}	Input Capacitance			1250	1810	
C _{oss}	Output Capacitance	V _{DS} = -30V , V _{GS} = 0V , F= 1MHz		85	125	pF
C _{rss}	Reverse Transfer Capacitance			65	95	
Rg	Gate resistance	V_{GS} =0V , V_{DS} =0V , F=1MHz		15	30	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ا _s	Continuous Source Current	$V_{G}=V_{D}=0V$, Force Current			-4.7	Α
I _{SM}	Pulsed Source Current				-9.4	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S = -1A , T _J =25°C			-1	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.



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Characteristics Curves

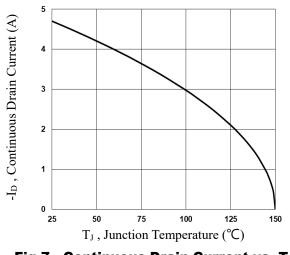
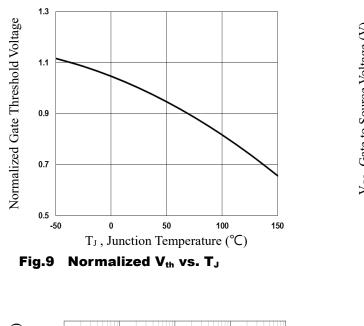
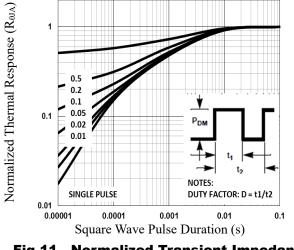


Fig.7 Continuous Drain Current vs. Tc







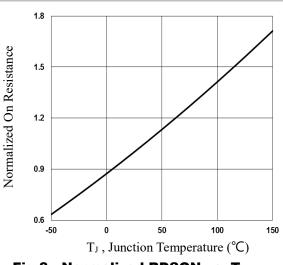


Fig.8 Normalized RDSON vs. T_J

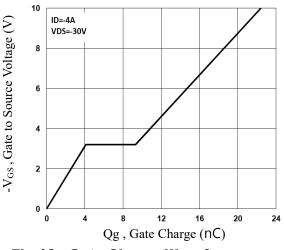


Fig.10 Gate Charge Waveform

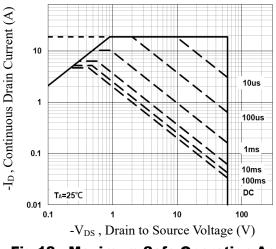
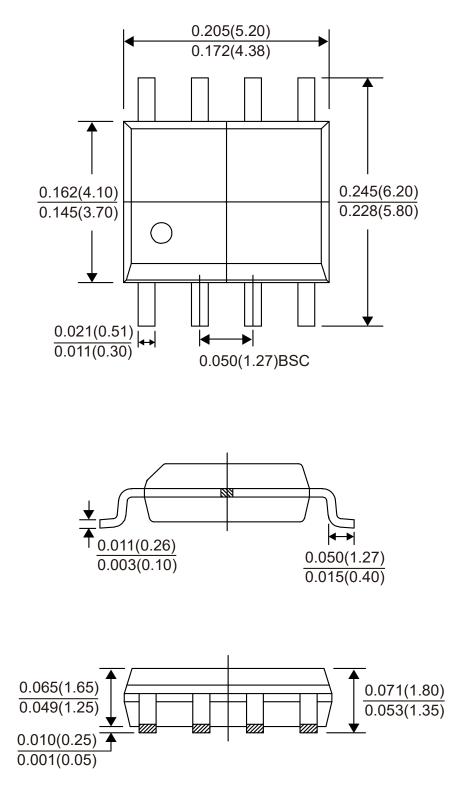


Fig.12 Maximum Safe Operation Area





Package Outline Dimensions



SOP-8 Dimensions in inches and (millimeters)





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